



Final Product Change Notification

202012016F01 : MPC7448 and MPC7447A epoxy underfill raw material change to new supplier

Note: This notice is NXP Company Proprietary.

Issue Date: May 12, 2021 **Effective date:** Aug 10, 2021

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Management summary

MPC7448 and MPC7447A Henkel FP4502 epoxy underfill raw material change to new supplier.

Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

PCN Overview

Description

NXP is pleased to announce the qualification of MPC7448 and MPC7447A epoxy underfill raw material from Resin A (supplier 1) to Resin B (supplier 2) to ensure supply continuity. Material property of Resin B is equivalent to Resin A. Hence the epoxy performance of Resin B is comparable to Resin A.

Reason

Resin A (supplier 1) was discontinued by the vendor. Resin B (supplier 2) was selected as the replacement and has comparable material properties to Resin A. There is no change to the underfill manufacturing process besides this material change.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jun 11, 2021.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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